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The present invention relates to the field of memory devices, and more particularly, to an integrated circuit that is capable of being used in a memory card for storing data in digital format. More particularly, 5 the present invention relates to a memory card of the multimedia type, i.e., capable of storing sounds and/or images (referred to hereafter as sounds/images) in digital format.

## 10

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These memory cards can be inserted directly

into a system for acquiring sounds/images in digital format, such as a DSC (Digital Still Camera), a video camera with DSC functionality, or an audio recorder for music and speech which transfers the sounds/images, after they have been acquired and digitized, to the memory card.

In general, with respect to sounds/images in digital format, the data stored in the memory card is subsequently transferred by a host processor apparatus, such as an ordinary personal computer, to media having a higher capacity, for example, a hard disk of the personal computer. In the host processor apparatus, the data can be processed by programs which require a computing power and a storage capacity which cannot be provided in the acquisition apparatus mentioned above. In such cases, memory cards are used for the temporary storage of the acquired data.

To make the memory card usable for the subsequent storage of new data, it has to be subjected to an operation of erasing the data previously stored on it. Typically, this erasure does not take place in the acquisition system itself, but is carried out in the host processor apparatus used for transferring the data from the card to the larger-capacity memory (off-line erasure). A memory card of the type currently used for sounds/images in digital format comprises an outer casing incorporating an integrated circuit made from semiconductor material comprising one or more semiconductor memories, suitable for non-volatile data storage.

The memory cards currently in use conform to physical specifications set by international standards or by standards established by the manufacturers

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themselves, which make them compatible with personal computers. One of these standards has been established by the PCMCIA (Personal Computer Memory Card International Association).

5           The integrated circuits used in conventional memory cards use non-volatile semiconductor memories which are electrically erasable and programmable, such as the EEPROM type (Electrically Erasable Programmable Read Only Memory), or, preferably, the Flash EEPROM  
10 type. Recently, memory cards using read-only non-volatile semiconductor memories (ROM) have also become available, with the data written permanently onto them during the manufacture of the integrated circuit (Mask ROM). Memory cards of the latter type are used, for  
15 example, as storage media for music, in the same way as music CDs.

          The erasure of the data stored in electrically erasable and programmable memories, and, in particular, in Flash memories with internal  
20 architecture of the type known as NOR, requires, as is known, an appropriate pre-programming operation that includes a preliminary programming of all the memory cells in such a way as to bring them to the same logic level in order to prevent any of the memory cells from  
25 entering a state of depletion during the erasure.

          After this pre-programming, the electrical erasure of the stored data can take place. The control of the operations of erasing and programming Flash memories requires the presence of a microprocessor  
30 provided with a corresponding microprogram which may be of considerable complexity. Flash memories with architecture of the type known as NAND do not require pre-programming of the memory cells to be subjected to

erasure. However, memories with this second type of architecture have certain drawbacks with respect to the former type, especially with respect to the speed of reading the stored data.

- 5           An example of a memory card including Flash memories is described in U.S. Patent No. 5,663,901. In this patent, with reference to Figure 13A, a description is given of a memory card using a plurality of memories of the Flash EEPROM type. These memories  
10 are associated with a controller module provided with a microprocessor for controlling the exchange of data between the EEPROM memories and the external apparatus, which act as hosts for the memory card via interface storage registers. The controller module also comprises  
15 a controller for the memories, which is provided, in turn, with a timing signal generator.

- It should be noted that the necessity of using microprocessors for the implementation of particular memory control procedures, as well as the  
20 intrinsic complexity of Flash memories, make the production cost of memory cards particularly high. Furthermore, the use of complex controllers makes it very difficult to integrate the controllers on a single semiconductor chip, particularly on the chip used for  
25 the Flash memories, and requires the formation of electrical interconnections for the transfer of the data between the various chips, thus further increasing the costs of design and production.

- This is reflected in the final cost of the  
30 systems for acquiring and processing sounds/images which make use of memory cards, thus limiting their distribution essentially to professional use.

          It should also be noted that the electrical

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erasure and programming functionality offered by Flash memories according to the procedures dictated by the technological characteristics of the memory does not appear to be imposed by requirements emerging from their application to the field of the acquisition of sounds/images in digital format. In this field of application, complete erasure of the memory before a subsequent use is required in all cases.

## Summary of the Invention

10 In view of the foregoing background, an  
object of the present invention is to provide an  
integrated circuit made from semiconductor material  
which is capable of being used in memory cards for the  
non-volatile storage of data in digital format,  
15 particularly, but not exclusively, for application in  
systems for acquiring and processing sounds/images,  
which permits a reduction of the production costs of  
the memory cards with respect to the memory cards of  
the known type, while maintaining compatibility with  
20 the conventional systems for acquiring data in digital  
format.

This and other objects, features and advantages are provided by an integrated circuit made from semiconductor material capable of storing data in digital format, particularly for application in a memory card which can be associated for operation with an external acquisition system and an external processing system.

The integrated circuit comprises input/output  
30 means for receiving the data from the external  
acquisition system or from the external processing  
system, for sending the data to the external processing

apparatus and for receiving a digital circuit-command signal from the system and from the apparatus. An electrically programmable non-volatile memory stores the digital data, and comprises a first terminal for an  
5 electrical programming signal capable of enabling the storage of the data available in the input/output means and a second terminal for an electrical read signal capable of enabling the output of the data from the memory to make them available in the input/output  
10 means.

The integrated circuit further comprises memory control means connected to the first and second terminals and to the input/output means for generating the electrical signals for programming and reading the  
15 memory from the command signal. The memory is of the type which can be erased by exposure to electromagnetic radiation, particularly ultraviolet radiation, to permit the non-electrical erasure of the stored data.

Also according to the present invention, a  
20 memory card is provided for storing data in digital format, with the card being associated for operation with an external acquisition system for receiving and storing data, and with an external processing apparatus for making the stored data available to the processing  
25 apparatus.

The memory card comprises an outer casing incorporating an integrated circuit made from semiconductor material capable of storing the data, and a non-volatile electrically programmable memory  
30 integrated in the circuit. The memory is of the type that can be erased by exposure to an external source of electromagnetic radiation of suitable wavelength, particularly ultraviolet radiation, and in that the



according to the present invention with a host processing system; and

Figure 10 schematically shows the internal structure of the adapter of Figures 9a and 9b.

5      **Detailed Description of the Preferred Embodiments**

With reference to the drawings, and in particular to Figures 1, 2 and 3, these drawings show schematically, a top plan view in Figure 1, a cross section view in Figure 2, and a bottom perspective view in Figure 3 of a memory card 100 for multimedia applications according to the present invention. The memory card 100 comprises a containment casing 102, made from a plastic material of the type commonly used for memory cards, i.e., pre-molded plastic, 15 thermosetting for injection molding.

The dimensions of the casing preferably conforms to one of the existing standards for memory cards, for example the MMC (MultiMedia Card) standard, thus making the memory card compatible with the 20 equipment already available on the market. The casing 102 contains a semiconductor chip in which is formed an integrated circuit comprising a memory 101 of the non-volatile electrically programmable type, for example, an EPROM (Erasable Programmable Read Only Memory).

25      An aperture 103 formed in the casing 102 at the position of the EPROM memory 101 allows an electromagnetic radiation of appropriate wavelength, for example ultraviolet radiation preferably having a wavelength of approximately 250 nm, generated 30 externally, to strike the EPROM memory 101 located inside the casing.



The memory card 100 also comprises electrical macroterminals or pins which enable the memory card to be connected electrically to an external host system that is capable of receiving the memory card 100 and with which the card is to be interfaced. The number of pins of the memory card depends on the standard to which the memory card conforms. For example, in the MMC standard the memory card has seven pins 1-7, arranged in such a way as to be accessible from external the casing, preferably on the side of the casing opposite the aperture 103.

The following description will refer, for simplicity, to a memory card conforming to the MMC standard. In this standard, pin 1 (RSV) is a terminal which is not connected in existing memory cards, but has been provided for applications which may be necessary in the future. Pin 2 (CMD) is a terminal for a bidirectional command/response signal, i.e., the CMD signal which is suitably encoded. This signal can be generated by an external system such as a system for acquiring and digitizing sounds/images, or a host processing system for discharging and/or processing is data, and carries the instructions for formatting the memory card and the instructions for programming or for reading data to/from the memory 101. Moreover, the CMD signal can be generated by the memory card and carries data relating to the current state of the memory card.

Pin 3 (VSS1) is a first ground terminal. Pin 4 (VDD) is a terminal through which a supply voltage Vcc is supplied to the memory card. Pin 5 (CLK) is a terminal for supplying a timing or clock signal, CLK, to the memory card. Pin 6 (VSS2) is a second ground terminal. Two separate ground terminals (VSS1 and VSS2)

are provided to increase the immunity to switching noise of the integrated circuits incorporated in the memory card. Pin 7 (DAT) is a terminal of the memory card which can be connected to a bidirectional input and output line, I/O, on which the data to be stored or already stored in the memory card 100, and the addresses of the memory locations in which the data are to be stored or are already stored, can travel in a serial mode.

10               With reference to Figure 2, the casing 102 comprises a container 104 and a cover 105 in which the aperture 103 is formed in a suitable position. Inside the container 104 is a printed circuit board (PCB) 107 to which the integrated-circuit semiconductor chip 106 15 is applied. The chip 106 is provided with contact pads (not shown in Figure 2) for the connection of electrical conducting wires 108 (bonding wires) to the PCB 107. The EPROM memory 101 is integrated in the integrated-circuit chip 106.

20               On the PCB 107, tracks of conductive material are formed. These are connected to the bonding wires 108, and extend to the pins 2-7 (as stated above, pin 1 is not connected in existing memory cards according to the MMC standard), which are accessible from external 25 the memory card 100, in such a way that the pins 2-7 are brought into electrical contact with corresponding contact pads on the chip 106, which act as microterminals of the integrated circuit 106.

              The pins 1-7 are tracks of conductive 30 material of suitable dimensions provided on the PCB 107. As shown in Figure 3, the container 104 has, on its underside, a gap 104' through which the terminals 1-7 of the PCB 107 are accessible. The cover 105 is

shaped in such a way as to form, when fitted on the container 104, a cavity 110 in which the integrated circuit 106 is housed. The aperture 103 formed in the cover 105 communicates with the cavity 110.

5           The aperture 103 and the cavity 110 are provided with protective means which are capable of mechanically protecting the integrated-circuit chip 106 located on the PCB 107 beneath them, providing thermal insulation, preventing infiltration of water, and at 10 the same time allowing the passage of ultraviolet radiation capable of erasing the EPROM memory 101. For example, the cavity 110 can be filled with polyaniline.

          The memory card 100 is preferably provided with reversible closing means to enable the aperture 15 103 to be closed and reopened for the passage of the ultraviolet radiation. Preferably, an adhesive element (not shown), capable of preventing the passage of light whose ultraviolet components might cause undesired erasures of the EPROM memory, is applied to the memory 20 card 100 at the position of the aperture 103. This adhesive element is such that it can be removed to allow the erasure of the memory through the aperture 103.

          Figure 4 shows, in the form of a simplified 25 block diagram, an integrated-circuit chip 106 made from semiconductor material on which is integrated a circuit capable of storing data in digital format. The integrated-circuit chip 106 comprises the EPROM memory 101 and a control device 111 including a first register 30 109, a decoder 114, an instruction memory 112 and a second register 113.

          Additionally, the chip 106 is provided with microterminals (contact pads) 2'-7' which can be



signal PGM (Program) for enabling the programming of the memory 101. Additionally, the memory 101 comprises a plurality of terminals 140 for the input/output of data in digital format.

- 5           The instruction memory 112 is capable of storing the instructions relating to the control of the memory 101, particularly those relating to programming and reading. The instruction memory 112 therefore implements, by a set of microinstructions, i.e.,
- 10   firmware stored therein, the protocol (commands, enabling signals, etc.) of the specific standard to which the memory card conforms. To make the production process particularly advantageous, the instruction memory 112 has a physical structure similar to that of
- 15   the memory 101, being, for example, of the EPROM type like the memory 101.

- The first register 109 is connected by a transfer line 114' to the microterminal 2' of the chip 106, which will consequently be electrically connected
- 20   to the corresponding pin 2 of the memory card to receive the encoded command/response signal CMD in serial form arriving from (or sent to) an external system for acquiring and digitizing sounds/images, or from an external apparatus for processing these data.
- 25   Additionally, the first register 109 is connected to the microterminal 5', which in turn will be connected to pin 4 of the memory card, to receive the timing signal CLK.

- The first register 109, of the shift type,
- 30   can be used to carry out a serial/parallel conversion (or vice versa) from the line 114' to a bus 114''. The first register 109 is timed by the timing signal CLK which is supplied to the memory card by the external

system (i.e., system for acquiring sounds/images or host processor) in which it is inserted. The decoder 114 is capable of decoding the signal CMD arriving from the register 109, making available on output lines 115  
5 address signals for the instruction memory 112, capable of selecting the locations of the instruction memory 112 and consequently the microinstructions stored in it.

By means of these addresses, the instruction  
10 memory 112 can be used to make available, on its output lines 117, 118, 119 respectively, the signal OE, the signal CE, and the signal PGM for controlling the memory 101 according to the command received. The terminals 140 of the memory 101 are connected to data  
15 input/output lines forming a bus 121. The data leaving the memory 101 or the data to be stored in the memory 101 can be transferred along these data input/output lines.

The second register 113, of the shift type,  
20 is connected by a single line 122, capable of serially transferring the addresses for the memory 101 and the data for input/output to/from the memory 101 to the microterminal 7', which in turn will be connected to pin 7 of the memory card. Additionally, the register  
25 113 is connected to the bus 121 of the data input/output lines of the memory 101, and also to an address-line bus 130', connected to the terminals 130 of the memory 101. The second register 113 can be used to carry out a serial/parallel conversion (and vice  
30 versa) from the line 122 to the bus 121 for the data in digital format in transit. The register 113 is timed by an external timing signal CLK, supplied through pin 5 of the memory card to the microterminal 5', to which

the register 113 is connected. The lines 122 and 114' are a particular example of possible input/output means capable of receiving/sending the data in digital format and capable of receiving/sending command signals of the integrated circuit on the chip 106.

The control device 111 can be made with means of controlling the memory 101 which are different from those described, but in any case are capable of generating, from the command signals supplied on the microterminal 2', the aforementioned signals for enabling the memory, for enabling programming, and for enabling the reading of the memory.

The microterminals 3' and 6' can be connected to ground and the microterminal 4' is suitable for receiving the supply voltage  $V_{cc}$ . For clarity of representation, Figure 4 does not show the electrical connections between the pads 4', 3' and 6' and the registers 109 and 113, the decoder 114, the instruction memory 112 and the EPROM memory 101, since these connections will be obvious to a person skilled in the art.

Figure 4 also shows an optional bus 116 which, as described in detail below, is used for programming the instruction memory 112. In other words, the bus is used for storing the appropriate firmware for making the memory card functionally compatible with the predetermined standard. The instruction memory 112 is programmed by sending the data, corresponding to the microinstructions, to be stored in the memory 112, through pin 7 connected to the microterminal 7', while the addresses of the locations in the memory 112 in which the

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microinstructions are to be stored are supplied through pin 2, which is connected to the microterminal 2'.

If the instruction memory 112 is also a memory which can be erased by electromagnetic radiation of suitable wavelength, typically ultraviolet radiation, and in particular if it is an EPROM memory, the integrated circuit on the semiconductor chip 106 is provided with a metallic layer on part of its surface. This metallic layer, which can be produced, for example, by a suitable degree of metallization specified in the manufacturing process stream, is capable of covering the region of the chip corresponding to the instruction memory 112 and serves to reflect the electromagnetic radiation emitted by an external source and used for erasing the memory 101.

Thus the memory 112 is not struck by the radiation and the instructions stored in it are not erased. In place of the metallic layer, or in addition to this layer, it is possible to use other means of protecting the memory 112. For example, the aperture 103 in the memory card can be formed only at a position in the region of the integrated circuit comprising the memory 101, and the containment casing 102 can be non-transparent to the radiation for erasing the memory 112.

The different components shown schematically in Figure 4 and the electrical connections between them can be produced by conventional integration techniques. Preferably, the control device 111 and the memory 101 are formed on a single chip of semiconductor material, but they can also be formed on a plurality of separate chips connected electrically by suitable metallic tracks formed on a printed circuit board (PCB) on which



these chips are mounted.

The memory card described up to this point is of the type called Chip On Board (COB), since the integrated circuit or circuits are directly mounted on one or more printed circuit boards (PCBs). In an alternative version of the memory card 100, the chip 106 in which is formed the integrated circuit for storing the data in digital format can be incorporated in a corresponding container (package), which is then mounted on a printed circuit board by conventional techniques, such as surface mounting.

The operation of programming the memory card 100 comprising the chip 106, in other words the writing of the data to the memory 101, takes place in the following way. The addresses and the data in digital format, supplied through pin 7 of the memory card to the microterminal 7', are transferred in serial mode, and in synchronization with the signal CLK, through the line 122, to the second register 113.

20           The second register 113, in synchronization  
with the signal CLK, loads these addresses and data.  
When the register 113 has been loaded with an address  
to be supplied to the memory 101 to identify a location  
of the memory, and with a byte or a word of data, the  
25 register makes its content available on the buses 130'  
and 121 respectively.

The command signal CMD supplied in serial mode to the microterminal 2' is loaded, in synchronization with the timing signal CLK, into the first register 109. The first register 109 then makes the data byte or word loaded in it available on the bus 114'.

The command signal carrying a write



location 101 whose content is to be read is supplied, again in serial mode, through the microterminal 7'. The register 113, timed by the timing signal CLK supplied through the microterminal 5', carries out a serial/parallel conversion and, through the bus 130', supplies to the memory 101 the address of the memory location which is to be read.

The enabling of the outputs of the memory 101 causes the data read at the addressed locations to be transferred in parallel mode via the bus 121 to the second register 113. After it has been loaded, the second register 113, timed by the timing signal, transfers the stored data to the line 122 in serial mode, to make them available at the output of the microterminal 7'.

The stored data are erased by subjecting the memory 101 to ultraviolet radiation. As is known, the ultraviolet radiation supplies the electrons trapped in the floating gates of the memory cells with the energy necessary to overcome the potential barrier which was trapping them. This removal of the charges from the floating gates corresponds to the erasure of the stored information from the memory cells. For the instruction memory 112, the erasure is prevented by the presence of the protective metallic layer.

It should be noted that the non-electrical erasure of the memory 101, although carried out simply by exposure to electromagnetic radiation, makes the production of the control devices 111 considerably less complicated and less costly than the production of controllers that include true microprocessors, as used in conventional memory cards, which have to control complex algorithms for the electrical erasure of Flash

memories.

Following exposure to the ultraviolet radiation, all the data stored in the memory 101 are erased, and the memory card 100 can be used for storing 5 new data. It should be noted that the memory card 100 can have different dimensions, different external shapes or a different number of pins from those shown by way of example, according to the standard to which it relates.

- 10           The modifications to be made to the memory card 100 to match it to a specific standard will be evident to a person skilled in the art from the present description and the figures. In particular, the memory card 100 can be adapted to various existing standards 15 while using the same integrated circuit.

- The presence of the bus 116 enables the instructions, to be stored in the instruction memory 112, to be entered through the bus 116 after the integrated-circuit chip 106 has been produced. The use 20 of an EPROM memory as the instruction memory 112 offers the memory card manufacturer a high degree of flexibility, by releasing him from the restrictions of the specific standard with which conformity is desired.

- The choice of the standard to which the 25 memory card is to conform can be made at the time of manufacture, without the need for modifications to the integrated structure, simply by storing, by electrical programming of the memory 112, the appropriate microprogram, by a process which does not in any way 30 involve the physical structure of the integrated circuit.

Figure 5 shows a semiconductor integrated-circuit chip 106' forming an alternative variation of

the chip 106. The components identical to those of Figure 4 are indicated in Figure 5 by the same numeric references and will not be described further.

The bus 114'' running from the first register 5 109 not only supplies the decoder 114, but also supplies an addressable multiplexer 150 via a bus 154. The multiplexer 150 is capable of switching between two different operating states, corresponding to the connection of an output bus 116'' of the multiplexer 10 150 to the bus 114'' or to a bus 116'. The bus 116' comprises the lines 117, 118, 119 running from the instruction memory 112, which carry signals for controlling the memory 101, for example the signals OE, PGM and CE.

15 The multiplexer 150 can be switched between the two operating states according to an enabling signal supplied to an input 155 of the multiplexer. This input 155 of the multiplexer 150 is connected to a switch 151 which can be connected selectively to a 20 ground terminal 152 and to a terminal 153 which can receive a signal which can command it to switch.

The multiplexer 150 is integrated in the chip 106', as is the switch 151, which comprises, for example, registers permanently programmable at the 25 place of manufacture, for selecting the operating mode. These registers can easily be implemented as UPROM cells, in other words EPROM cells suitably protected by a layer of metallization to prevent their exposure to ultraviolet radiation.

30 When the switch 151 is in a state such that the input 155 of the multiplexer 150 is connected to the ground terminal 152, the memory 101 is connected, via the bus 116'', to the bus 116' and therefore to the

instruction memory 112. In this case, the integrated chip 106' has the same functionality as the chip 106.

When the switch 151 is in a state such that the input 155 of the multiplexer 150 is connected to the terminal 153, an enabling signal supplied to the terminal 153, and therefore to the terminal 155, causes the multiplexer 150 to connect the output bus to the bus 114'' running from the register 109. In this case the memory 101 is not connected to the instruction memory 112, and can receive the signals CE, OE, PGM, and any other signals necessary for controlling its operation, directly from external the chip 106' through the microterminal 2'.

The bus 114'' and the multiplexer 150 thus form special bypass means which can be used to bypass the decoder 114 and the instruction memory 112, and therefore the controller 111, by connecting the memory 101 directly to the output of the register 109. In this case, microinstructions, supplied in serial mode to the microterminal 2' and converted from serial to parallel by the register 109, can reach the memory 101.

The possibility, provided by the multiplexer 150, of connecting the EPROM memory 101 to, or disconnecting it from, the instruction memory 112 enables the chip 106' to be used not only within the memory card 100, but also for other applications not requiring the functions provided by the controller 111, or in the present case by the decoder 114 and the instruction memory 112. For example, the integrated circuit of Figure 4 can be used as a conventional EPROM memory when not within a memory card. This increases the flexibility of the integrated circuit 106', since the manufacturer does not have to provide different

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production lines for the manufacture of integrated circuits having purely memory functions and integrated circuits for memory cards.

Where the chip 106' is concerned, the choice between using the integrated circuit for a memory card or for another type of application can be made simply by modifying a single photolithographic mask among those provided in the process stream for the manufacture of the integrated circuit, specifically the mask which determines the metallization lines. Alternatively, it is possible to use non-volatile registers comprising UPROM cells, without modifying any photolithographic mask.

The memory card 100 is particularly suitable for applications of the multimedia type. In other words, it can be used for the acquisition of sounds/images in digital format. The memory card 100 can form part of an acquisition and digitization system (hereafter termed acquisition system) for sounds/images, such as a DSC (Digital Still Camera), a video camera with DSC functionality, or an audio recorder for music and speech, and can also be inserted in a personal computer, thus becoming a mass storage medium in exactly the same way as a system disk.

This acquisition system is provided with an appropriate socket having electrical terminals which can come into contact with pins 1-7 of the memory card 100. The acquisition system supplies to pins 1-7 of the memory card 100 the data to be stored, and also the supply voltage Vcc (equal to 5 V, for example) and the ground connections, the command signal CMD, the timing signal CLK, and the signal DAT. The signals required for programming are made available from pins 2-7 of the

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memory 100 by the generation of electromagnetic radiation by the lamp 304. The lamp 304 can be illuminated by energy supplied by the processor and can be controlled by the latter by the logic circuits 307.

- 5 After the erasure, the memory card 100 can be re-used for storing new data acquired by the system 200.

Figures 9a, 9b and Figure 10 in combination show a further device 400 for interfacing between the memory card 100 and a host processor 450. The

- 10 interfacing device 400 is external to the processor 450, particularly a non-portable personal computer, in a desktop or tower configuration, and is connected to it by a suitable connecting means 401. This connecting means can be, for example, a serial or parallel bus  
15 provided with a suitable plug 403, for example an adapter for connection to a serial port 404 of the personal computer. This serial port 404 is, for example, a USB (Universal Serial Bus) port of the processing apparatus 450.

- 20 This interfacing device 400 comprises a socket 402 which houses the memory card 100 and is provided with electrical terminals 411-417 capable of electrically and mechanically contacting pins 1-7 of the memory card 100 when this is housed in the socket  
25 402. These electrical terminals 411-417 are connected to logic circuits 451 which are, in turn, connected by a plug 401' to the connecting means 401.

- Additionally, the device 400 comprises a lamp 304, similar to the lamp used in the adapter 300,  
30 provided with the step-up transformer 305. The supply voltage for the lamp is supplied through the USB bus of the personal computer. The logic circuits 451, on the other hand, control the illumination of the lamp. The

logic circuits 451 also enable the memory card to be interfaced with the USB protocol. Advantageously, the lamp 304 can be associated with reflective means, for example a metallic plate 408, to reflect the radiation  
5 emitted from the lamp 304 towards the socket 402 housing the memory card 100.

Preferably, the device 400 is provided with two indicator lamps 406 and 407, of different colors for example, which can signal, respectively, that the  
10 data are being transferred from the memory card 100 to the memory of the processing apparatus, and that the data are being erased.